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Microelectronics Packaging Handbook, Part 2: Semiconductor ...

Microelectronics Packaging Handbook, Part 2: Semiconductor Packaging (Pt. 1) by Rao Tummala (1997-01-31) Hardcover – January 1, 1997 by Alan G. Klopfenstein (Auth Rao Tummala (Author), Eugene J. Rymaszewski (Author) (Author)

Microelectronics Packaging Handbook, Part 2: Semiconductor ...

Part 2, chapters 7 through 14, covers the interconnection of the IC chip to the first level of packaging and all first level packages. Part 2 also includes electrical test as well as sealing and encapsulation technologies. Part 3, chapters 15 through 20, covers board level packaging as well as connectors, cables, and optical packaging.

MICROELECTRONICS PACKAGING HANDBOOK

Part II: Semiconductor Packaging discusses the interconnection of the IC chip to the first level of packaging and all first level packages. Electrical test, sealing, and encapsulation technologies are also covered in detail.

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Microelectronics Packaging Handbook Technology Drivers Part I. Authors: Tummala, Rao, Rymaszewski, Eugene J., Klopfenstein, Alan G. Free Preview

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The second-level packaging consists of the connection of the microelectronic package to the PCB. Additional protection of encapsulated microelectronics on PCBs can be achieved by the application of a polymer coating [12]. PCBs may be further interconnected to a motherboard, known as third-level packaging.

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ME 6226: Fundamentals of Semiconductor Manufacture and ...

In addition, the volumes contain over 2000 references, 900 figures, and 250 tables. Part I: Technology Drivers covers the driving force of microelectronics packaging - electrical, thermal, and reliability. It introduces the technology developer to aspects of manufacturing that must be considered during product development.